



RECOMMEND PCB LAYOUT
(THICKNESS: 0.8 OR 1.00mm)

NOTES:

1. MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
GOLD PLATED Min ON CONTACT AREA, 100u"
Min TIN (LEAD FREE) ON SOLDER AREA,
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHLD: SUS304-H,T=0.12±0.03mm
2. MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N AFTER TEST.
DURABILITY: 10000 CYCLES
3. ELECTRICAL:
CURRENT: 5A FOR VBUS;
1.25A FOR GND PIN.
0.25A FOR OTHER.
VOLTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC R.M.S.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
4. ENVIRONMENTAL
TEMPERATURE RANGE -25°C ~ +85°C

USCX-24MX-XXMX-02

- 1-G.P
- 2-ROHS
- 3-REACH
- 4-HF/无卤
- B-半金弯锡 1u"
- D-半金弯锡 5u"
- F-半金弯锡 15u"
- H-半金弯锡 30u"
- 1-卷带包装
- 2-4V/1盒
- N-可焊锡
- S-弯锡
- T-无锡
- A-金
- K-黑色
- N-本色

深圳市精拓金电子有限公司

产品图

PRODUCT CHART DWG

公差一览表

公差一览表

公差	公差	公差	公差
X	±0.25	X	±5.°
X	±0.20	X	±2.°
XX	±0.15	XX	±1.°
XXX	±0.05	XXX	±0.5°

单位	MM	制图	邱建辉	制图料号	USB 3.1 C TYPE
UNITS	MM	DRAWING	审核	产品名称	SMT公头
SCALE	1:1	CHD	郭治富	PRODUCT NO	
DATE	2016.08.04	核准	黄国荣	角法	版本
		APPD		VIEW	VER